



## ABSTRACT

This document describes the known exceptions to the functional specifications (advisories).

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## 1 Functional Advisories

Advisories that affect the device's operation, function, or parametrics.

✓ The check mark indicates that the issue is present in the specified revision.

Errata Number	Rev C
<a href="#">FLL3</a>	✓
<a href="#">PORT3</a>	✓
<a href="#">TA12</a>	✓
<a href="#">TA16</a>	✓
<a href="#">TA21</a>	✓
<a href="#">TAB22</a>	✓
<a href="#">WDG2</a>	✓
<a href="#">XOSC7</a>	✓

## 2 Preprogrammed Software Advisories

Advisories that affect factory-programmed software.

✓ The check mark indicates that the issue is present in the specified revision.

The device does not have any errata for this category.

## 3 Debug Only Advisories

Advisories that affect only debug operation.

✓ The check mark indicates that the issue is present in the specified revision.

Errata Number	Rev C
<a href="#">EEM20</a>	✓

## 4 Fixed by Compiler Advisories

Advisories that are resolved by compiler workaround. Refer to each advisory for the IDE and compiler versions with a workaround.

✓ The check mark indicates that the issue is present in the specified revision.

Errata Number	Rev C
<a href="#">CPU4</a>	✓

Refer to the following MSP430 compiler documentation for more details about the CPU bugs workarounds.

### TI MSP430 Compiler Tools (Code Composer Studio IDE)

- [MSP430 Optimizing C/C++ Compiler](#): Check the --silicon\_errata option
- [MSP430 Assembly Language Tools](#)

### MSP430 GNU Compiler (MSP430-GCC)

- [MSP430 GCC Options](#): Check -msilicon-errata= and -msilicon-errata-warn= options
- [MSP430 GCC User's Guide](#)

### IAR Embedded Workbench

- [IAR workarounds for msp430 hardware issues](#)

## 5 Nomenclature, Package Symbolization, and Revision Identification

The revision of the device can be identified by the revision letter on the [Package Markings](#) or by the [HW\\_ID](#) located inside the TLV structure of the device.

### 5.1 Device Nomenclature

To designate the stages in the product development cycle, TI assigns prefixes to the part numbers of all MSP MCU devices. Each MSP MCU commercial family member has one of two prefixes: MSP or XMS. These prefixes represent evolutionary stages of product development from engineering prototypes (XMS) through fully qualified production devices (MSP).

**XMS** – Experimental device that is not necessarily representative of the final device's electrical specifications

**MSP** – Fully qualified production device

Support tool naming prefixes:

**X**: Development-support product that has not yet completed Texas Instruments internal qualification testing.

**null**: Fully-qualified development-support product.

XMS devices and X development-support tools are shipped against the following disclaimer:

"Developmental product is intended for internal evaluation purposes."

MSP devices have been characterized fully, and the quality and reliability of the device have been demonstrated fully. TI's standard warranty applies.

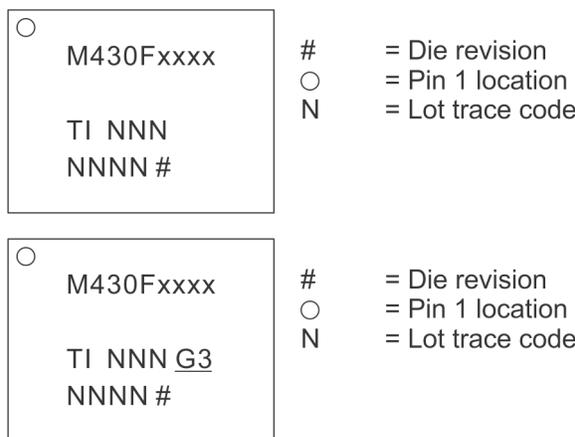
Predictions show that prototype devices (XMS) have a greater failure rate than the standard production devices. TI recommends that these devices not be used in any production system because their expected end-use failure rate still is undefined. Only qualified production devices are to be used.

TI device nomenclature also includes a suffix with the device family name. This suffix indicates the temperature range, package type, and distribution format.

### 5.2 Package Markings

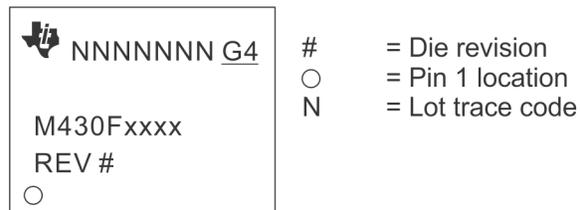
**RTD64**

**QFN (RTD), 64 Pin**



**PM64**

**LQFP (PM), 64 Pin**



### 5.3 Memory-Mapped Hardware Revision (TLV Structure)

This device does not support reading the hardware revision from memory.

Further guidance on how to locate the TLV structure and read out the HW\_ID can be found in the device User's Guide.

## 6 Advisory Descriptions

### CPU4

#### *CPU Module*

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**Category**

Compiler-Fixed

**Function**

PUSH #4, PUSH #8

**Description**

The single operand instruction PUSH cannot use the internal constants (CG) 4 and 8. The other internal constants (0, 1, 2, -1) can be used. The number of clock cycles is different:

PUSH #CG uses address mode 00, requiring 3 cycles, 1 word instruction

PUSH #4/#8 uses address mode 11, requiring 5 cycles, 2 word instruction

**Workaround**

Refer to the table below for compiler-specific fix implementation information.

IDE/Compiler	Version Number	Notes
IAR Embedded Workbench	IAR EW430 v2.x until v6.20	User is required to add the compiler flag option below. --hw_workaround=CPU4
IAR Embedded Workbench	IAR EW430 v6.20 or later	Workaround is automatically enabled
TI MSP430 Compiler Tools (Code Composer Studio)	v1.1 or later	
MSP430 GNU Compiler (MSP430-GCC)	MSP430-GCC 4.9 build 167 or later	

### EEM20

#### *EEM Module*

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**Category**

Debug

**Function**

Debugger might clear interrupt flags

**Description**

During debugging read-sensitive interrupt flags might be cleared as soon as the debugger stops. This is valid in both single-stepping and free run modes.

**Workaround**

None.

### FLL3

#### *FLL Module*

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**Category**

Functional

**Function**

FLLDx = 11 for /8 may generate an unstable MCLK frequency

**Description**

When setting the FLL to higher frequencies using FLLDx = 11 (/8) the output frequency of the FLL may have a larger frequency variation (e.g. averaged over 2sec) as well as a lower average output frequency than expected when compared to the other FLLDx bit settings.

**Workaround**

None

### PORT3

#### *PORT Module*

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**Category**

Functional

<b>Function</b>	Port interrupts can get lost
<b>Description</b>	Port interrupts can get lost if they occur during CPU access of the P1IFG and P2IFG registers.
<b>Workaround</b>	None

## TA12 *TA Module*

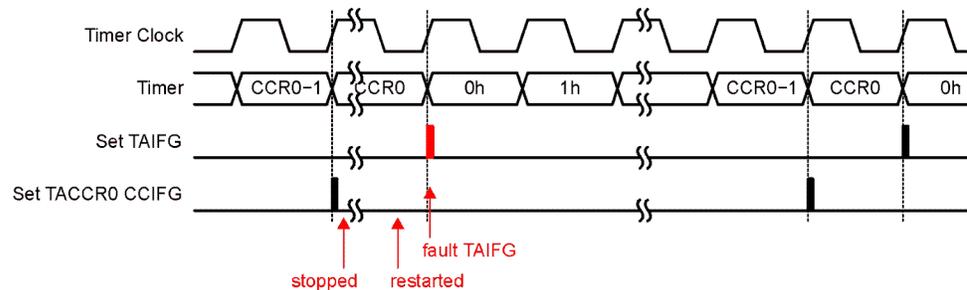
<b>Category</b>	Functional
<b>Function</b>	Interrupt is lost (slow ACLK)
<b>Description</b>	Timer_A counter is running with slow clock (external TACLK or ACLK) compared to MCLK. The compare mode is selected for the capture/compare channel and the CCRx register is incremented by one with the occurring compare interrupt (if TAR = CCRx). Due to the fast MCLK the CCRx register increment (CCRx = CCRx+1) happens before the Timer_A counter has incremented again. Therefore the next compare interrupt should happen at once with the next Timer_A counter increment (if TAR = CCRx + 1). This interrupt gets lost.
<b>Workaround</b>	Switch capture/compare mode to capture mode before the CCRx register increment. Switch back to compare mode afterwards.

## TA16 *TA Module*

<b>Category</b>	Functional
<b>Function</b>	First increment of TAR erroneous when IDx > 00
<b>Description</b>	The first increment of TAR after any timer clear event (POR/TACLK) happens immediately following the first positive edge of the selected clock source (INCLK, SMCLK, ACLK or TACLK). This is independent of the clock input divider settings (ID0, ID1). All following TAR increments are performed correctly with the selected IDx settings.
<b>Workaround</b>	None

## TA21 *TA Module*

<b>Category</b>	Functional
<b>Function</b>	TAIFG Flag is erroneously set after Timer A restarts in Up Mode
<b>Description</b>	In Up Mode, the TAIFG flag should only be set when the timer counts from TACCR0 to zero. However, if the Timer A is stopped at TAR = TACCR0, then cleared (TAR=0) by setting the TACLK bit, and finally restarted in Up Mode, the next rising edge of the TACLK will erroneously set the TAIFG flag.



<b>Workaround</b>	None.
<b>TAB22</b>	<b><i>TAB Module</i></b>
<b>Category</b>	Functional
<b>Function</b>	Timer_A/Timer_B register modification after Watchdog Timer PUC
<b>Description</b>	Unwanted modification of the Timer_A/Timer_B registers TACTL/TBCTL and TAIV/TBIV can occur when a PUC is generated by the Watchdog Timer(WDT) in Watchdog mode and any Timer_A/Timer_B counter register TACCRx/TBCCRx is incremented/ decremented (Timer_A/Timer_B does not need to be running).
<b>Workaround</b>	Initialize TACTL/TBCTL register after the reset occurs using a MOV instruction (BIS/BIC may not fully initialize the register). TAIV/TBIV is automatically cleared following this initialization.  Example code:  MOV.W #VAL, &TACTL or MOV.W #VAL, &TBCTL  Where, VAL=0, if Timer is not used in application otherwise, user defined per desired function.
<b>WDG2</b>	<b><i>WDG Module</i></b>
<b>Category</b>	Functional
<b>Function</b>	Incorrectly accessing a flash control register
<b>Description</b>	If a key violation is caused by incorrectly accessing a flash control register, the watchdog interrupt flag is set in addition to the expected PUC.
<b>Workaround</b>	None
<b>XOSC7</b>	<b><i>XOSC Module</i></b>
<b>Category</b>	Functional
<b>Function</b>	Oscillation failure in LF mode at low temperatures
<b>Description</b>	When using LFX1 in LF mode along with the built-in crystal load capacitors, the resulting oscillation duty cycle may decrease, potentially to the point of no oscillation, under operating temperatures less than -10C.
<b>Workaround</b>	Disable the internal crystal load capacitance (XCAPxPF = 00) and use external load capacitors on XIN & XOUT as recommended by the crystal manufacturer.

## 7 Revision History

NOTE: Page numbers for previous revisions may differ from page numbers in the current version.

<b>Changes from May 29, 2018 to May 11, 2021</b>	<b>Page</b>
• Changed the document format and structure; updated the numbering format for tables, figures, and cross references throughout the document.....	<a href="#">5</a>

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